

MPI Corporation 6223.TT

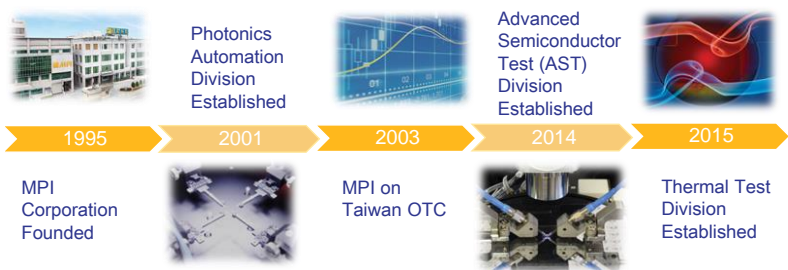
Merrill Lynch's APAC TMT Conference 2017
22/23 Mar

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Presentation Disclaimer

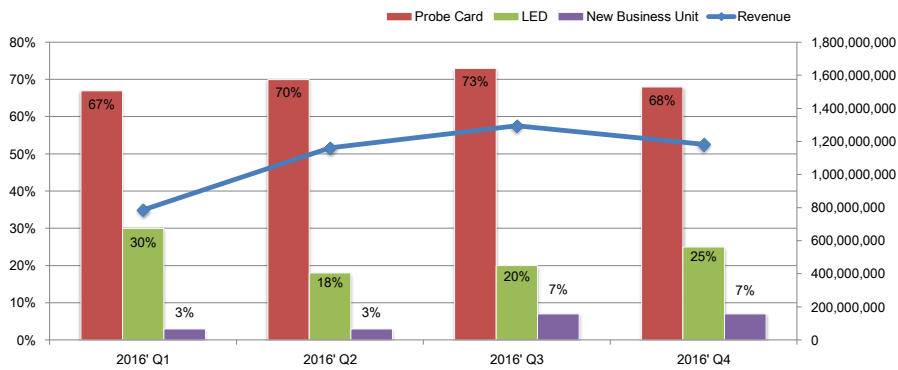
The information herein contains forward-looking statements. We have based these forward-looking statements on our current expectations and projections about future events. Although we believe that these expectations and projections are reasonable, such forward-looking statements are inherently subject to risks, uncertainties and assumptions about us, including, among other things: the intensely competitive Semi-conductor, and LED industries and markets; Cyclical nature of the semiconductor industry; Risks associated with global business activities; General economic and political conditions. All financial figures discussed herein are prepared pursuant to IFRS. All audited figures will be publicly announced upon the completion of our audited process.

Company at a Glance

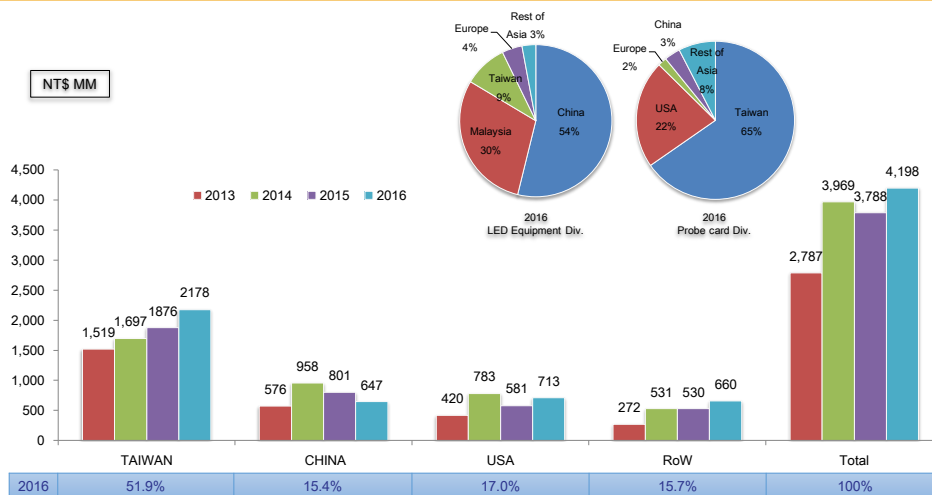


Founded	July, 25, 1995
Paid-in Capital	NTD\$ 796M (2017.2.28-the latest)
Employees	1451 (2017.2.28)

Business Portfolio



Net Sales by Geographic



Agenda

■ Business Contents

- Semi-conductor (Probe Card)
- Photonics Automation (LED)
- Thermal & AST

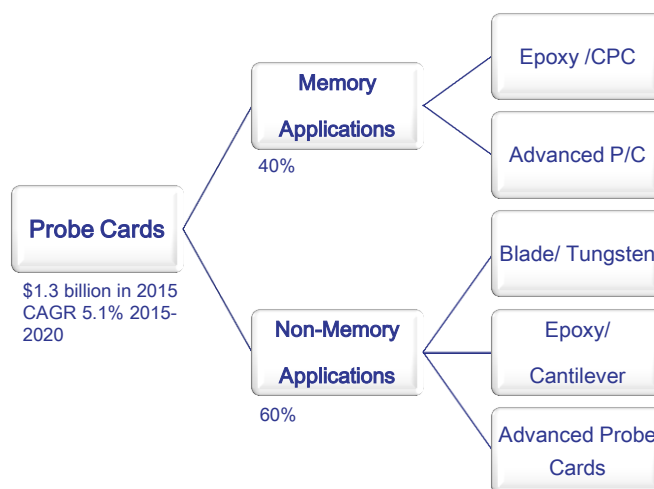
■ Financial Statements

Semi-conductor (Probe Card)

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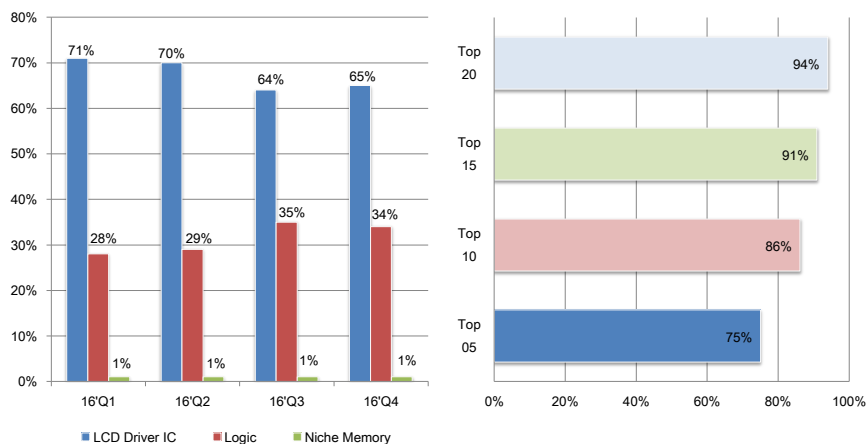
Global Probe Card Market Update



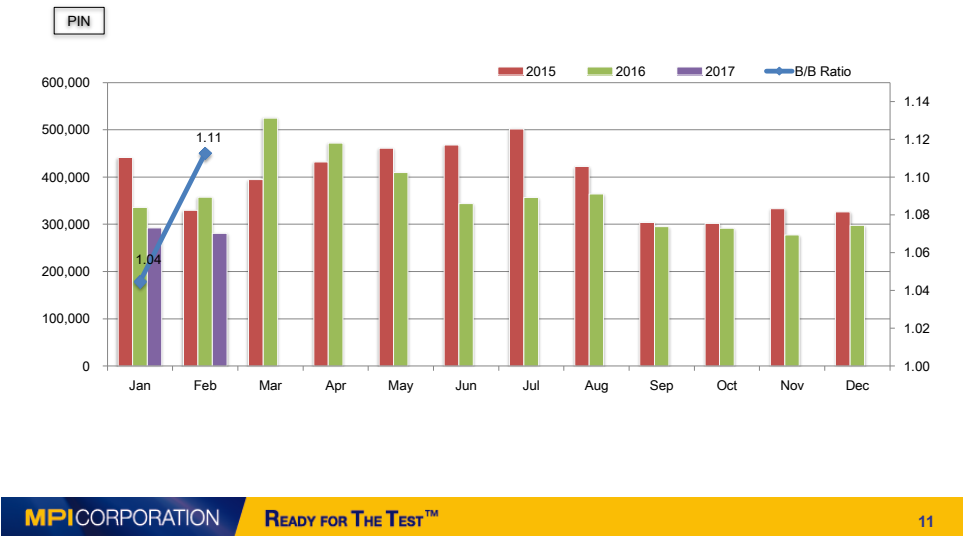
Top 10 Probe Card Vendors (2009-2015)

	(Rank)	2009	2010	2011	2012	2013	2014	2015
FormFactor, Inc.	USA	1	1	2	2	1	1	1
Micronics Japan Co., Ltd.	Japan	2	2	1	1	2	2	2
Technoprobe	Italy	4	4	4	4	3	3	3
Japan Electronic Materials	Japan	3	3	3	3	4	4	4
MPI Corporation	Taiwan	6	5	6	6	5	5	5
Cascade Microtech	USA	8	10	10	8	8	7	6
SV TCL	Singapore	5	6	8	9	10	9	7
Will Technology	Korea	7	7	7	5	6	10	8
Korea Instrument (KI)	Korea	10	8	5	7	9	6	9
Microfriend	Korea	9	9	9	10	7	8	10

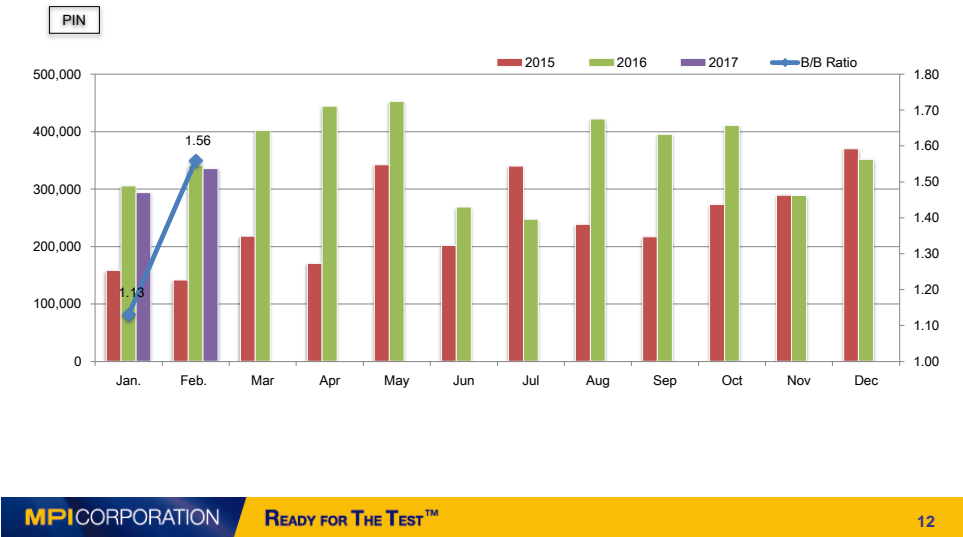
Product Mix of CPC (Cantilever)



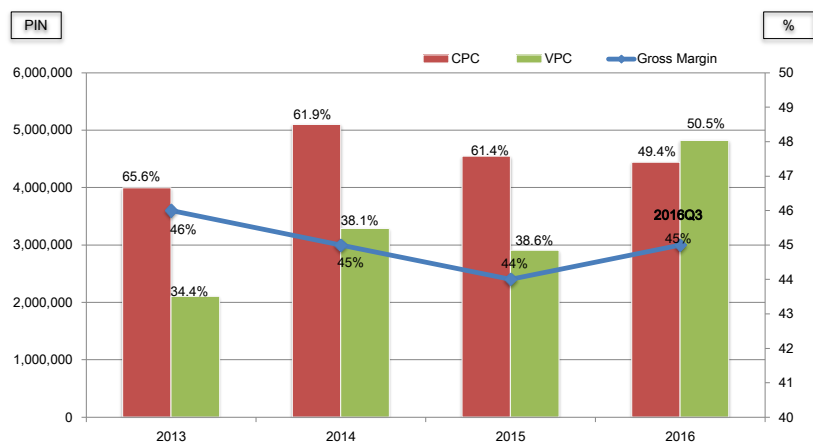
CPC Pin-Shipment



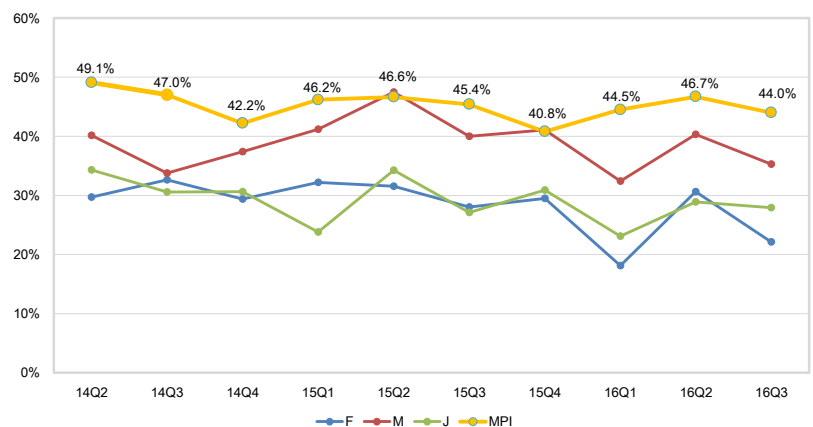
VPC Pin-Shipment



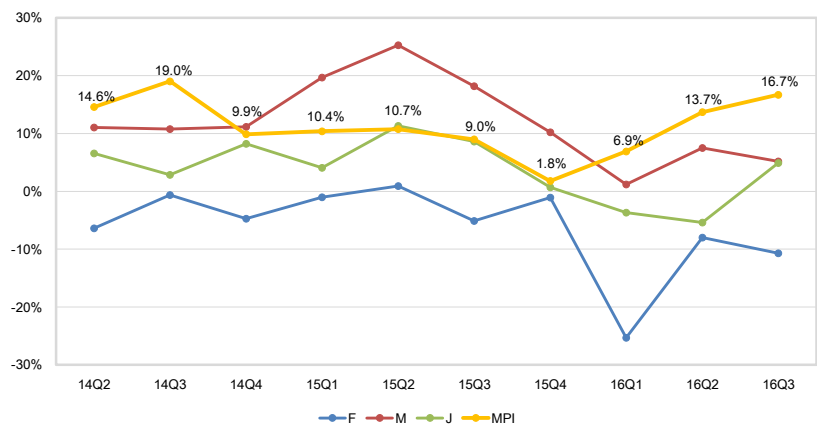
CPC and VPC Yearly Trend



Gross Margin Between Global Peers



Operating Margin Between Global Peers



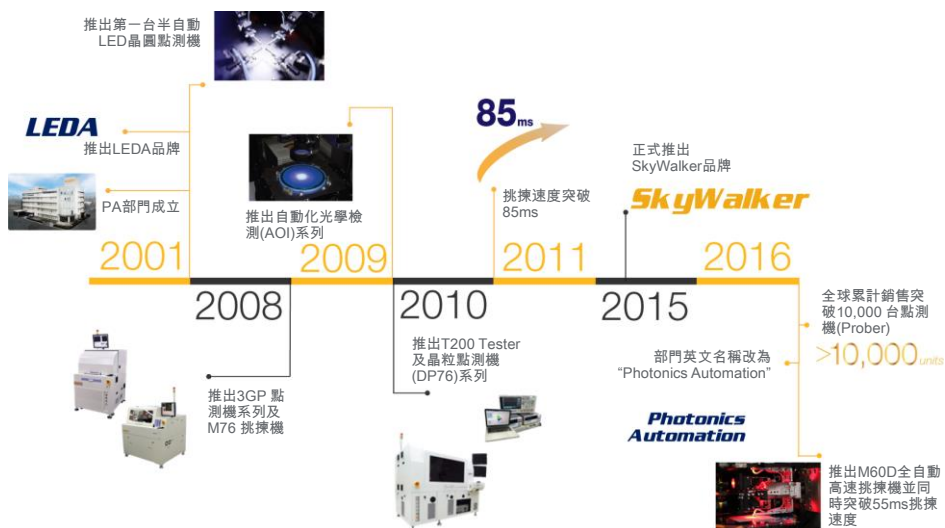
Photonics Automation (LED)

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Photonics Automation (PA) Overview




Milestone



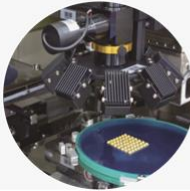
Main Product Line



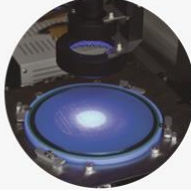
Probing System
 Wafer
 Flip chip
 Single die




Testing System
 Mass production software
 Integrated spectrum meter
 Integrated source meter




Chip Sorting
 Mapping sorter




Inspection System
 Chip after dicing
 Chip after sorting




Package Probing
 Panel
 Bottom probing
 Single package




Package Testing
 From low to high power




Package Level
 Chip Scale Package (CSP)
 Foil to Foil (FTF)



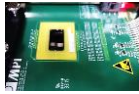
Wafer



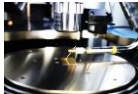
Tape



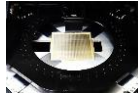
Die



Packaging Substrate



Photodiode(PD)



LED Package Probing

Wafer Technology Migration

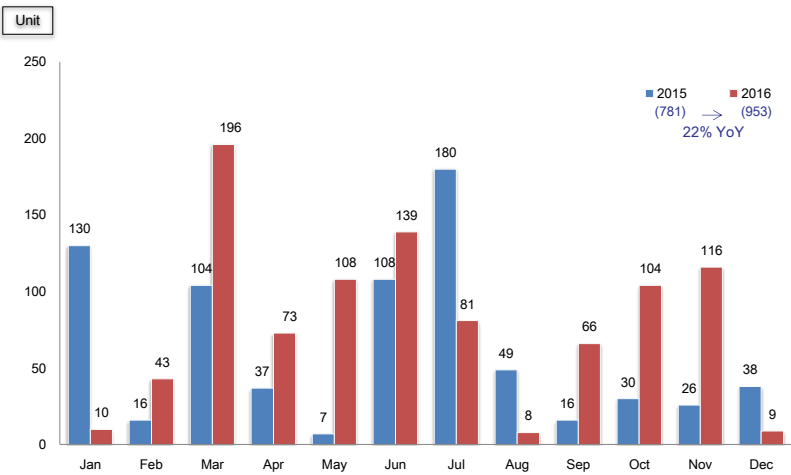
4"

6"

8"

<div>Prober</div> <div> <div>P7202</div> <div>3GS</div> <div>P80C4</div> </div>	<div> <div>P7602P</div> <div>4G</div> <div>P9000</div> </div>	<div> <div>P9000</div> <div>4G</div> <div>P9002</div> </div>
<div>AOI</div> <div> <div>A2000P</div> </div>	<div> <div>NEW</div> <div>A3000</div> </div>	
<div>Sorter</div> <div> <div>M76FP</div> </div>	<div> <div>M76V</div> </div>	<div> <div>NEW</div> <div>M60D</div> </div>

2016 Shipment



LED 2017 Targeting Markets



Automotive

Night Vision, Reverse Radar to
Panorama View for Autopilot
System
IR LED

Eye Scanning for E-wallet

IR LED (Fujitsu and Samsung)

VR (2016 Market size 14m USD)
IR LED

Inside-out Tracking : HTC Vive
Outside-in Tracking : Oculus Rift (Facebook)
More Manufacturers: Tencent, Nintendo,
Microsoft and Dell

New Business Unit (Thermal/AST)

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Thermal

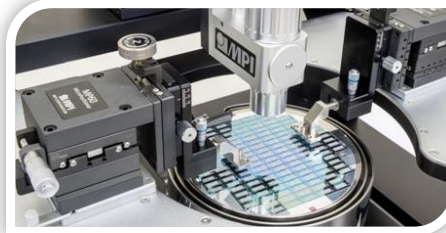


- Market size: roughly USD\$30m
- Industries: Telecom / Automotive
- Maximum capacity: 30 – 35 units

<http://www.mpi-thermal.com/media/>

AST

- **Market size:** roughly USD\$120m
- **Industry:** Foundry/IC design houses' engineering stage process



Financial Statements

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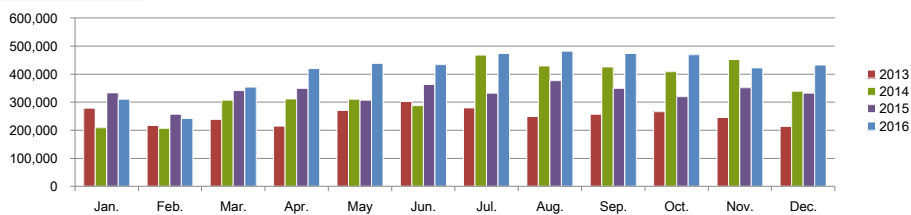
Balance Sheet Highlight

Amount: NT\$ Million	3Q 2016		3Q 2015	
Cash and Cash Equivalents	766	10%	549	8%
Fixed Assets	3,485	48%	3,384	51%
Total Assets	7,322	100%	6,659	100%
LT Debt	242	3%	252	4%
Shareholders' Equity	3,817	52%	3,680	56%
EBITDA	475		338	
*EBITDA=operating income + depreciation & amortization expenses				

Income Statement

NT\$1,000	2016 Q3		2015 Q3	
Net Sales	3,637,181	100%	3,009,613	100%
Cost of Goods Sold	1,998,477	55%	1,623,715	54%
Gross Profit	1,638,704	45%	1,385,898	46%
Operating Expense	1,160,009	32%	1,087,415	37%
Operating Income	478,862	13%	301,426	10%
Investment Income & Others	3,524		37,223	
Net Income (before tax)	405,531	11%	275,804	9%
EPS (before tax)	5.15		3.47	

Net Sales NT\$ 1,000



MPICORPORATION



Thank You



<http://www.mpi-corporation.com>

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